

BILL OF MATERIALS  
TIDA-01187 REV A

Item	Qty	Part Reference	Value	PCB Footprint	Mfr_Name	Mfr_Part_Number	Note
1	5	C51-C53,C76,C128	1uF	0402	MURATA	GRM155R60J105KE19D	OR EQUIVALENT
2	4	C54,C55,C113,C117	.1uF	0402	MURATA	GRM155R71C104KA88D	
3	0	C56,C70,C122	1uF	0402	MURATA	GRM155R60J105KE19D_DNI	DNI
4	18	C57-C64,C69,C71,C102-C107,C121,C123	.1uF	0402	TDK CORP	C1005X7R1E104K050BB	
5	9	C65,C72,C108-C110,C112,C114,C116,C124	10uF	1206	KEMET	C1206C106K3RACTU	
6	20	C66-C68,C78-C83,C111,C115,C118-C120,C130-C135	.01uF	0402	MURATA	GRM155R71H103KA88J	
7	0	C73,C125	1pF	0402	AVX	04025U1R0BAT2A_DNI	DNI
8	4	C74,C75,C126,C127	.1pF	0402	MURATA	GJM1555C1HR10WB01D	
9	2	C77,C129	1.5pF	0402	AMERICAN TECH CERAMICS	600L1R5AT200T	
10	2	D7,D9	LED RED	LED_0805	LITE ON	LTST-C170KRKT	
11	1	D8	1N5819	DIODE_SM_1N5819HW	DIODES INC	IN5819HW-7-F	
12	1	D10	LASER, PL90	DIODE_THVT_LASER	OSRAM OPTO SEMI	Q62702P1760	
13	1	D11	LED GREEN	LED_0603	LITE-ON	LTST-C190GKT	
14	2	D12,D14	PIN PHOTODIODE	DIODE_PIN_PHOTODIODE	OSRAM OPTO SEMI	SFH 2701	
15	4	FB5-FB8	120 OHM @ 100MHz	IND_0402	MURATA	BLM15AG121SN1	
16	4	J11,J12,J16,J22	HDR, THVT, 2POS, .100	HDR_THVT_1x2_100_M	SAMTEC	HTSW-102-07-G-S	
17							
18	0	J13,J23	HDR, THVT, 2POS, .100	HDR_THVT_1x2_100_M	SAMTEC	HTSW-102-07-G-S_DNI	DNI
19	2	J20,J21	HDR, THVT, 2POS, FRICTION LOCK	TERM_BLOCK_2_100	MOLEX	22-11-2022	
20	10	P5-P14	CONN, RF, THVT, JACK	SMP_B120	MOLEX	853050232	
21	6	PP4-PP9	PROBE_PAD_0603	PROBE_PAD_0603	TE CONNECTIVITY	RCU-0C	
22	2	R53,R58	1k	VAR_RES_THVT_PV36	BOURNS	PV36W102C01B00	
23	18	R54,R55,R59,R60,R63,R74,R79,R80,R82,R94,R95,R99,R102,R103,R105,R117,R118,R122	0	0402	PANASONIC	ERJ-2GE0R00X	
24	0	R56,R57,R61,R62,R64,R70-R72,R83,R96-R98,R106,R119-R121	0	0402	PANASONIC	ERJ-2GE0R00X_DNI	DNI
25	2	R65,R66	10	0402	PANASONIC	ERJ-2RKF10R0X	
26	6	R67,R76,R81,R88,R104,R111	10k	0402	PANASONIC	ERJ-2RKF1002X	
27	3	R68,R87,R110	1k	0402	PANASONIC	ERJ-2RKF1001X	
28	3	R69,R73,R93	402	0402	PANASONIC	ERJ-2RKF4020X	
29	1	R75	.05	0603	PANASONIC	ERJ-L03KF50MV	
30	0	R77,R78,R100,R101	49.9	0402	PANASONIC	ERJ-2RKF49R9X_DNI	DNI
31	4	R84,R85,R107,R108	2k	0402	PANASONIC	ERJ-2RKF2001X	
32	2	R86,R109	2.49k	0402	PANASONIC	ERJ-2RKF2491X	
33	4	R89,R90,R112,R113	374	0402	PANASONIC	ERJ-2RKF3740X	
34	4	R91,R92,R114,R115	3.4k	0402	PANASONIC	ERJ-2RKF3401X	
35	2	T2,T3	ADT2-1T+	TFMR_6_220x310_100	Mini-Circuits	ADT2-1T+	
36	1	U7	iC-HG	QFN_28_197x197_0P50MM_PWRPAD	iC Haus	iC-HG	
37	1	U8	CDCLVC1102	TSSOP_8_122X122_26	Texas Instruments	CDCLVC1102PW	
38	2	U9,U15	OPA857	VQFN_16_124X124_PWRPAD	Texas Instruments	OPA857IRGTT	
39	2	U10,U16	THS4541	QFN_16_124x124_RGT	Texas Instruments	THS4541IRGTT	
40	2	U13,U14	REG104GA-3.3	SOT_223_6_DCQ	Texas Instruments	REG104GA-3.3	
41	1	BARE BOARD			Texas Instruments	TIDA-01187 REV A	

NOTES:

1. DNI MEANS DO NOT INSTALL.
2. USE WATER SOLUBLE FLUX DURING BOARD ASSEMBLY.
3. ASSEMBLY MUST BE RoHS COMPLIANT AND LEAD FREE.

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